



BCP51T series

45 V, 1 A PNP medium power transistors

Rev. 1 — 29 April 2019

Product data sheet

1. Product profile

1.1. General description

PNP medium power transistors in a medium power SOT223 (SC73) Surface-Mounted Device (SMD) plastic package.

Table 1. Product overview

Type number	Package		NPN complement
	Nexperia	JEDEC	
BCP51T	SOT223	SC-73	BCP54T
BCP51-10T			BCP54-10T
BCP51-16T			BCP54-16T

1.2. Features and benefits

- High collector current capability I_C and I_{CM}
- Three current gain selections
- High power dissipation capability
- AEC-Q101 qualified

1.3. Applications

- Linear voltage regulators
- MOSFET drivers
- High-side switches
- Power management
- Amplifiers

1.4. Quick reference data

Table 2. Quick reference data

$T_{amb} = 25\text{ °C}$ unless otherwise specified.

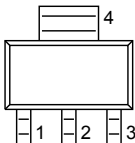
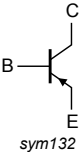
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base	-	-	-45	V
I_C	collector current		-	-	-1	A
I_{CM}	peak collector current	single pulse; $t_p \leq 1\text{ ms}$	-	-	-2	A

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
h_{FE}	DC current gain						
	BCP51T	$V_{CE} = -2 \text{ V}; I_C = -150 \text{ mA}$	[1]	63	-	250	
	BCP51-10T		[1]	63	-	160	
	BCP51-16T		[1]	100	-	250	

[1] pulsed; $t_p \leq 300 \text{ } \mu\text{s}$; $\delta \leq 0.02$

2. Pinning information

Table 3. Pinning

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	B	base		
2	C	collector		
3	E	emitter		
4	C	collector		

3. Ordering information

Table 4. Ordering information

Type number	Package		Version
	Name	Description	
BCP51T	SC-73	plastic, surface-mounted package with increased heatsink; 4 leads	SOT223
BCP51-10T			
BCP51-16T			

4. Marking

Table 5. Marking

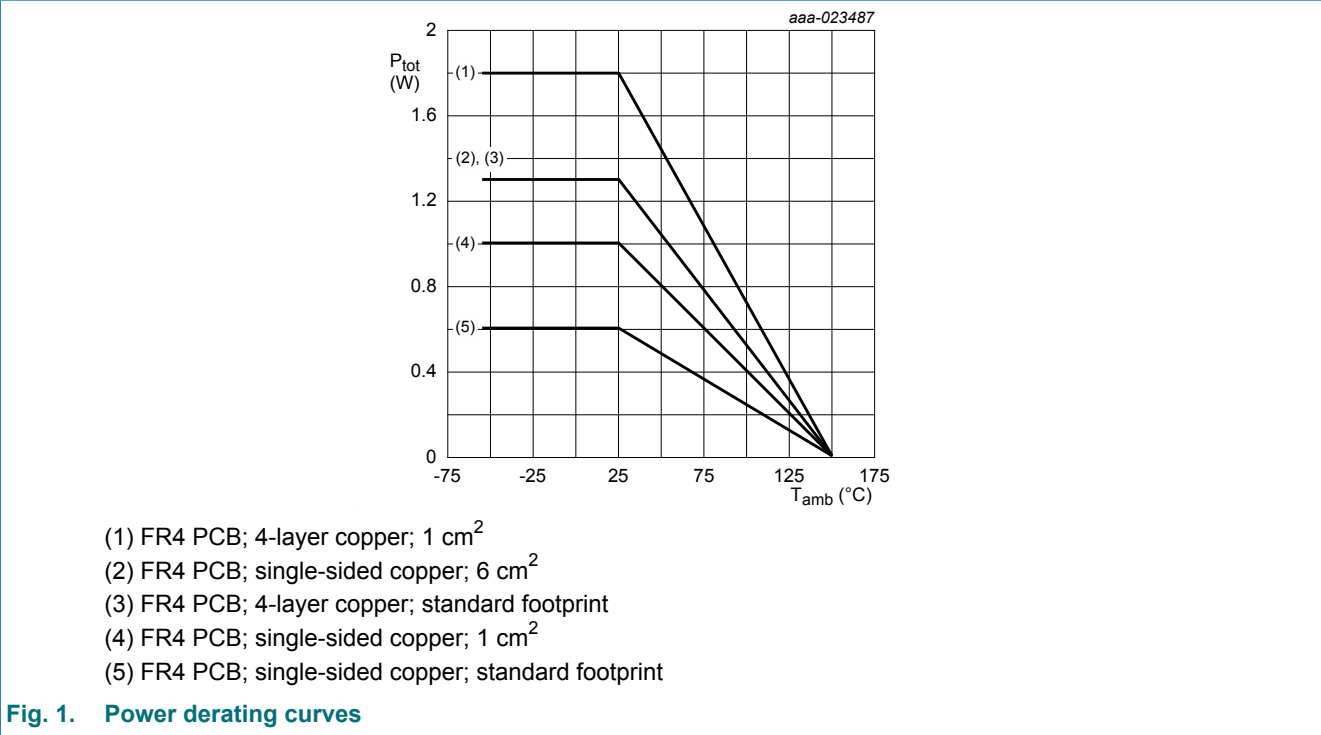
Type number	Marking code
BCP51T	BCP51T
BCP51-10T	P5110T
BCP51-16T	P5116T

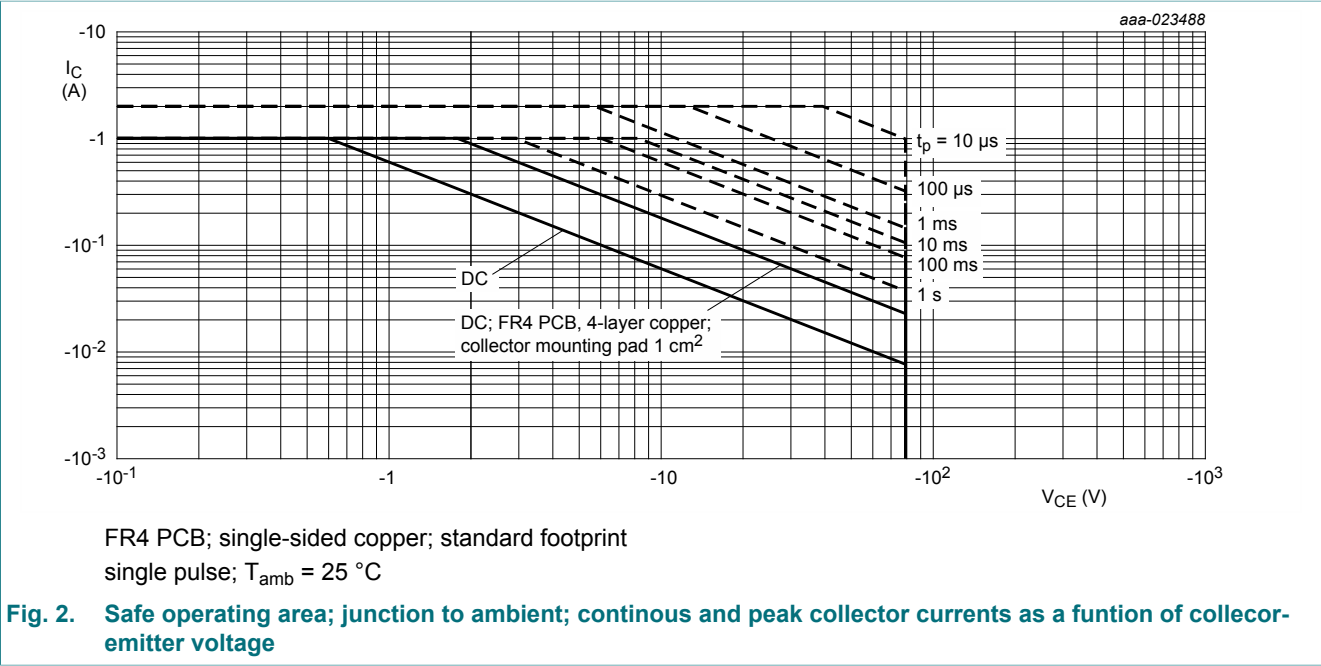
5. Limiting values

Table 6. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).
 $T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	-45	V
V_{CEO}	collector-emitter voltage	open base	-	-45	V
V_{EBO}	emitter-base voltage	open collector	-	-5	V
I_C	collector current		-	-1	A
I_{CM}	peak collector current	single pulse; $t_p \leq 1\text{ ms}$	-	-2	A
I_B	base current		-	-0.2	A
I_{BM}	peak base current	single pulse; $t_p \leq 1\text{ ms}$	-	-0.3	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ }^{\circ}\text{C}$ [1]	-	0.6	W
		[2]	-	1	W
		[3]	-	1.3	W
		[4]	-	1.3	W
		[5]	-	1.8	W
T_j	junction temperature		-	150	$^{\circ}\text{C}$
T_{amb}	ambient temperature		-55	150	$^{\circ}\text{C}$
T_{stg}	storage temperature		-65	150	$^{\circ}\text{C}$

- [1] Device mounted on an FR4 Printed-Circuit-Board (PCB); single-sided copper; tin-plated and standard footprint.
- [2] Device mounted on an FR4 Printed-Circuit-Board (PCB); single-sided copper; tin-plated; mounting pad for collector 1 cm².
- [3] Device mounted on an FR4 Printed-Circuit-Board (PCB); single-sided copper; tin-plated; mounting pad for collector 6 cm².
- [4] Device mounted on an FR4 Printed-Circuit-Board (PCB); 4-layer copper; tin-plated and standard footprint.
- [5] Device mounted on an FR4 Printed-Circuit-Board (PCB); 4-layer copper; tin-plated; mounting pad for collector 1 cm².





6. Thermal characteristics

Table 7. Thermal characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	209	K/W
			[2]			125	K/W
			[3]			97	K/W
			[4]	-	-	97	K/W
			[5]	-	-	70	K/W
$R_{(j-sp)}$	thermal resistance from junction to solder point			-	-	18	K/W

- [1] Device mounted on an FR4 Printed-Circuit-Board (PCB); single-sided copper; tin-plated and standard footprint.
[2] Device mounted on an FR4 Printed-Circuit-Board (PCB); single-sided copper; tin-plated; mounting pad for collector 1 cm².
[3] Device mounted on an FR4 Printed-Circuit-Board (PCB); single-sided copper; tin-plated; mounting pad for collector 6 cm².
[4] Device mounted on an FR4 Printed-Circuit-Board (PCB); 4-layer copper; tin-plated and standard footprint.
[5] Device mounted on an FR4 Printed-Circuit-Board (PCB); 4-layer copper; tin-plated; mounting pad for collector 1 cm².

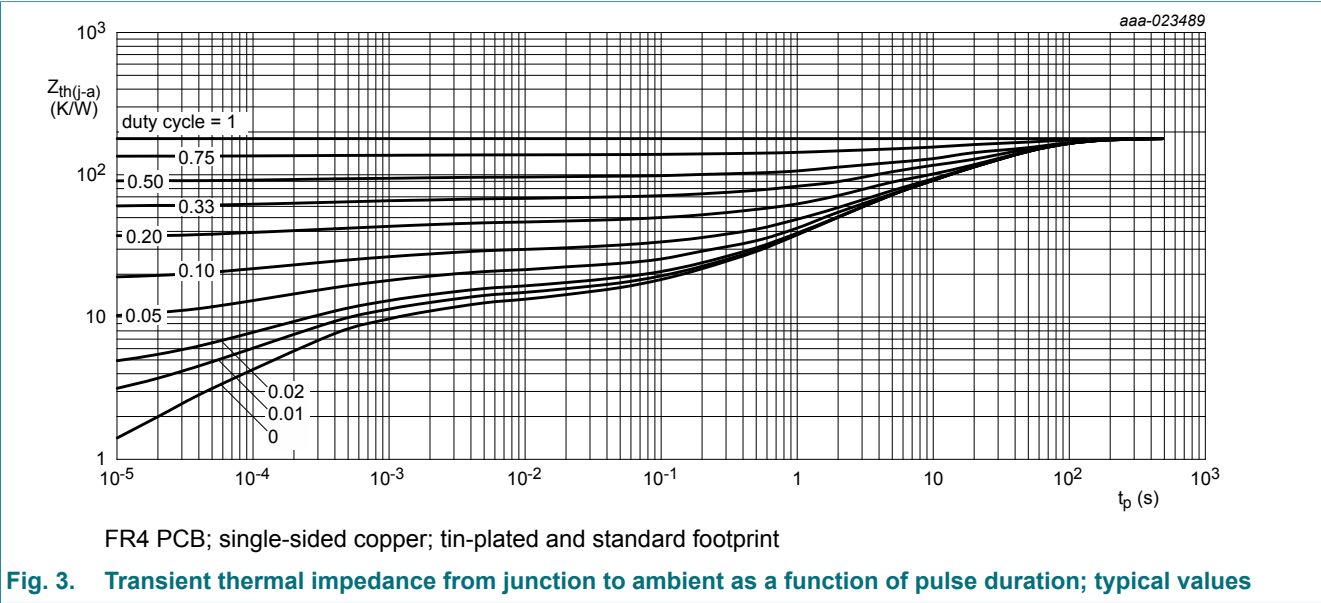
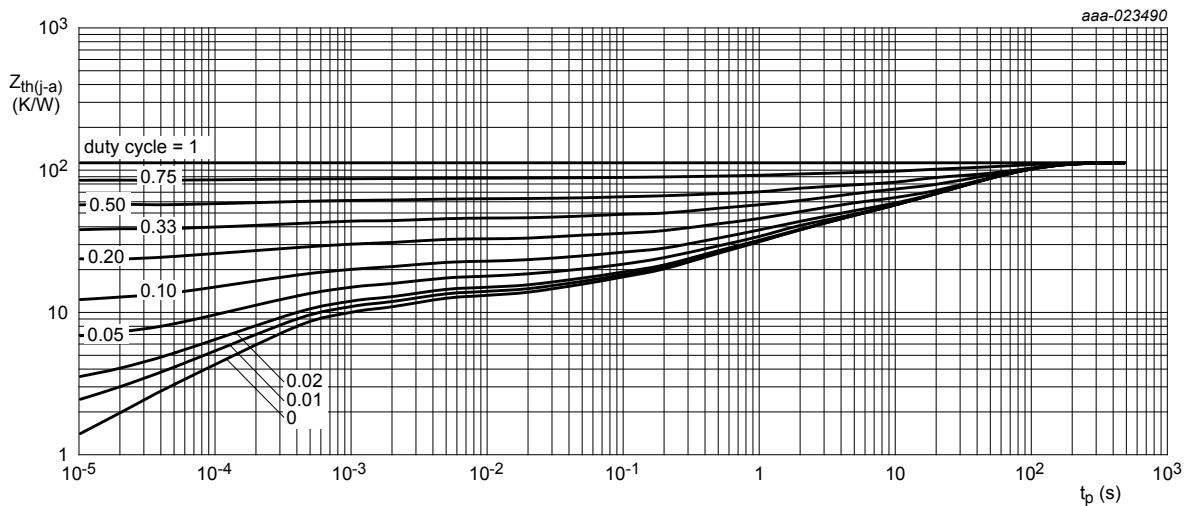
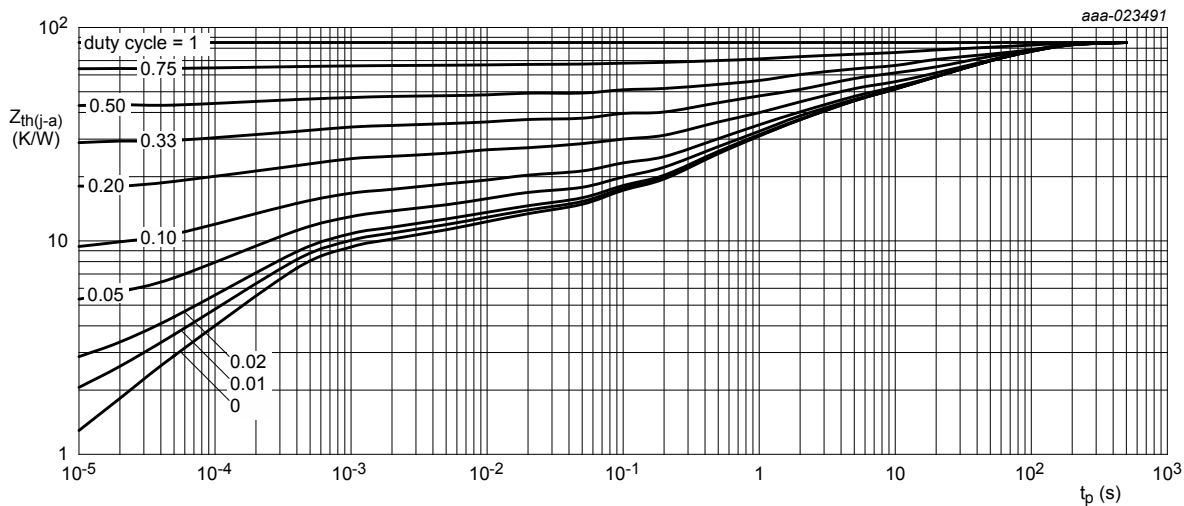


Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



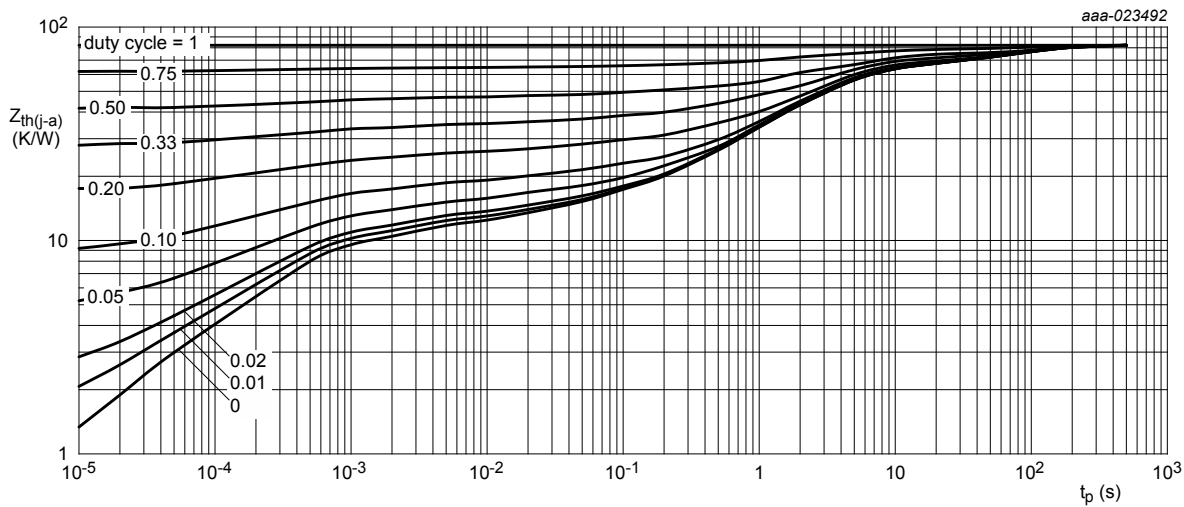
FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 1 cm²

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



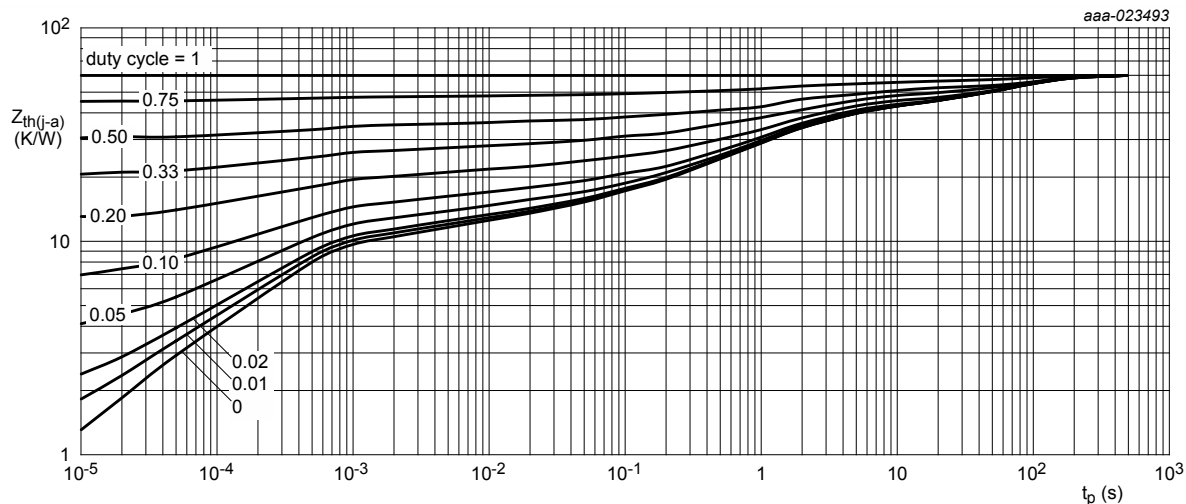
FR4 PCB; single-sided copper; tin-plated; mounting pad for collector 6 cm²

Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB; 4-layer copper; tin-plated and standard footprint

Fig. 6. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB; 4-layer copper; tin-plated; mounting pad for collector 1 cm²

Fig. 7. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

7. Characteristics

Table 8. Characteristics

$T_{amb} = 25\text{ °C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)CBO}$	collector-base breakdown voltage	$I_C = -100\text{ }\mu\text{A}$; $I_E = 0\text{ A}$	-45	-		V
$V_{(BR)CEO}$	collector-emitter breakdown voltage	$I_C = -2\text{ mA}$; $I_E = 0\text{ A}$	-45	-		V
$V_{(BR)EBO}$	emitter-base breakdown voltage	$I_E = -100\text{ }\mu\text{A}$; $I_C = 0\text{ A}$	-5	-		V
I_{CBO}	collector-base cut-off current	$V_{CB} = -30\text{ V}$; $I_E = 0\text{ A}$	-	-	-100	nA
		$V_{CB} = -30\text{ V}$; $I_E = 0\text{ A}$; $T_j = 150\text{ °C}$	-	-	-10	μA
I_{EBO}	emitter-base cut-off current	$V_{EB} = -5\text{ V}$; $I_C = 0\text{ A}$	-	-	-100	nA
h_{FE}	DC current gain					
	BCP51T, -10T, -16T	$V_{CE} = -2\text{ V}$; $I_C = -5\text{ mA}$		63	-	-
		$V_{CE} = -2\text{ V}$; $I_C = -500\text{ mA}$	[1]	40	-	-
	BCP51T	$V_{CE} = -2\text{ V}$; $I_C = -150\text{ mA}$	[1]	63	-	250
	BCP51-10T	$V_{CE} = -2\text{ V}$; $I_C = -150\text{ mA}$	[1]	63	-	160
	BCP51-16T	$V_{CE} = -2\text{ V}$; $I_C = -150\text{ mA}$	[1]	100	-	250
V_{CEsat}	collector-emitter saturation voltage	$I_C = -500\text{ mA}$; $I_B = -50\text{ mA}$	[1]	-	-	-500 mV
V_{BE}	base-emitter voltage	$V_{CE} = -2\text{ V}$; $I_C = -500\text{ mA}$	[1]	-	-	-1 V
f_T	transition frequency	$V_{CE} = -5\text{ V}$; $I_C = -50\text{ mA}$; $f = 100\text{ MHz}$		100	140	- MHz
C_c	collector capacitance	$V_{CB} = -10\text{ V}$; $I_E = I_C = 0\text{ A}$; $f = 1\text{ MHz}$		-	7	- pF

[1] pulsed; $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$

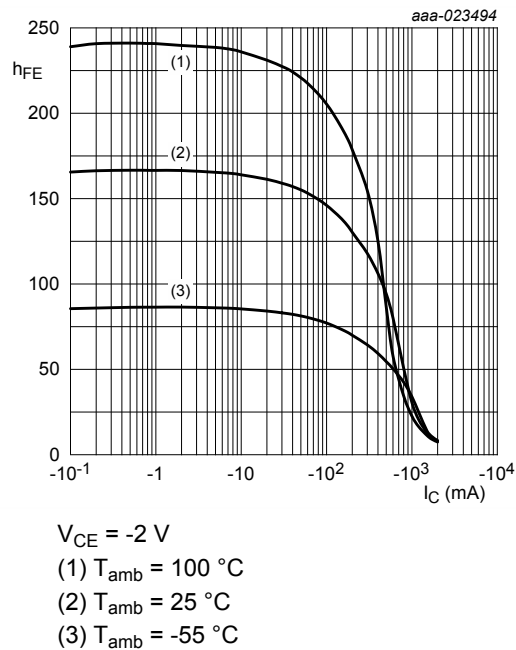


Fig. 8. DC current gain as a function of collector current; typical values

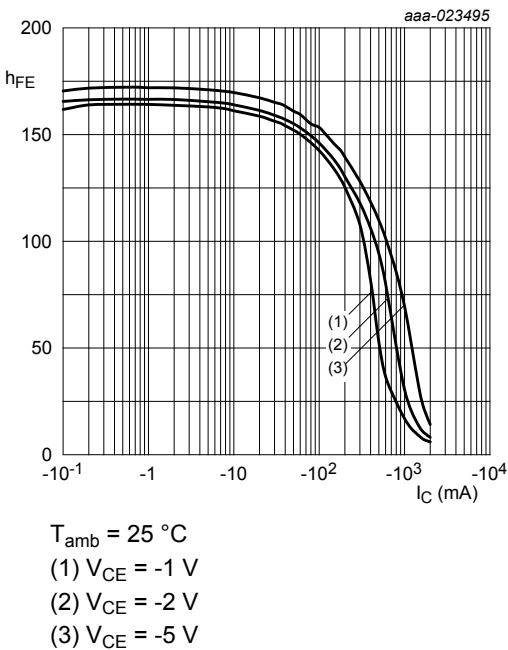


Fig. 9. DC current gain as a function of collector current; typical values

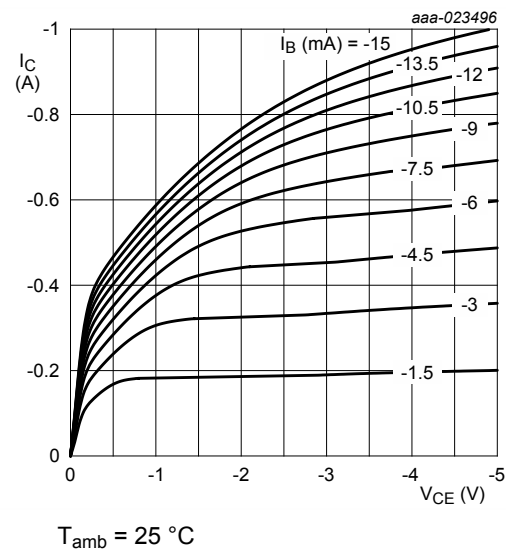


Fig. 10. Collector current as a function of collector-emitter voltage; typical values

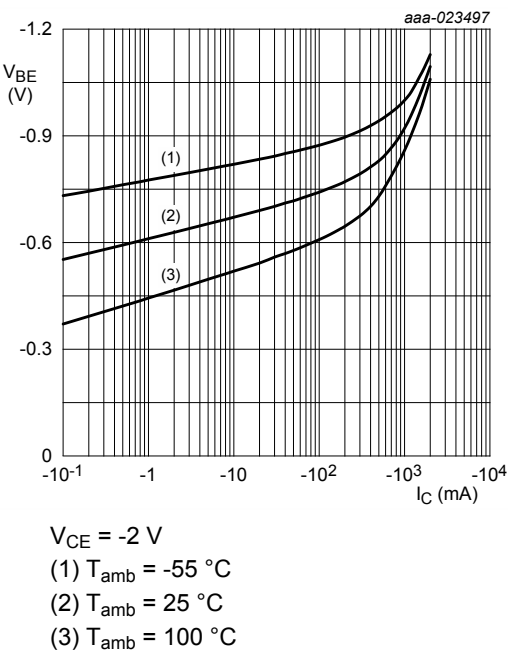


Fig. 11. Base-emitter voltage as a function of collector current; typical values

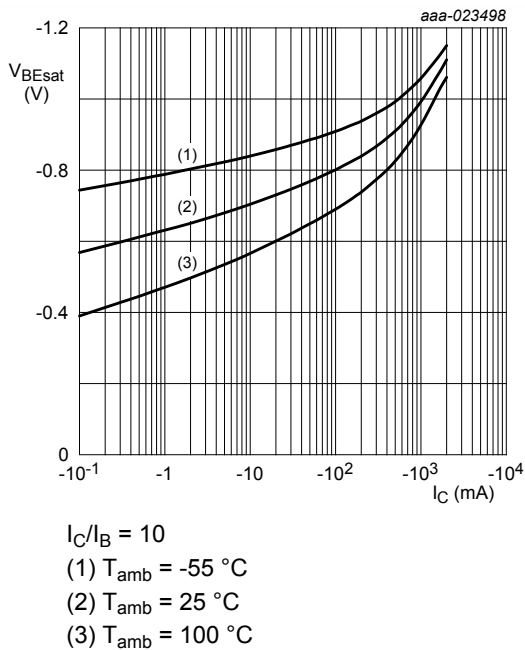


Fig. 12. Base-emitter saturation voltage as a function of collector current; typical values

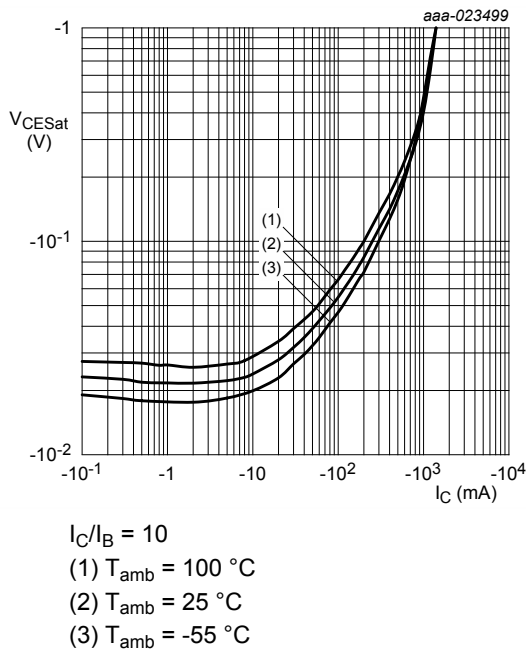


Fig. 13. Collector-emitter saturation voltage as a function of collector current; typical values

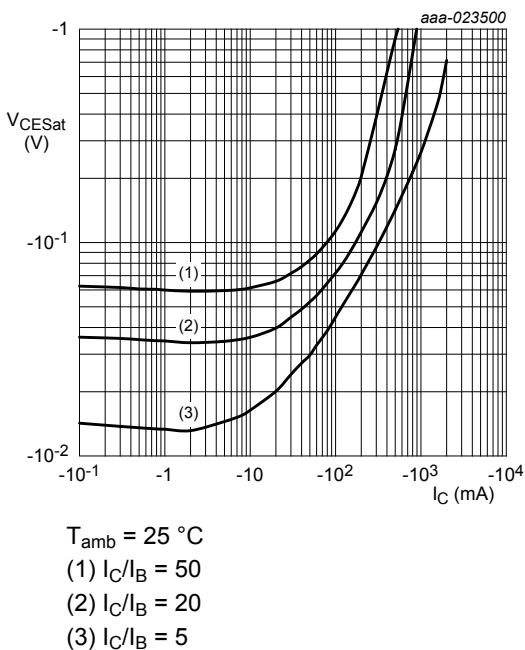


Fig. 14. Collector-emitter saturation voltage as a function of collector current; typical values

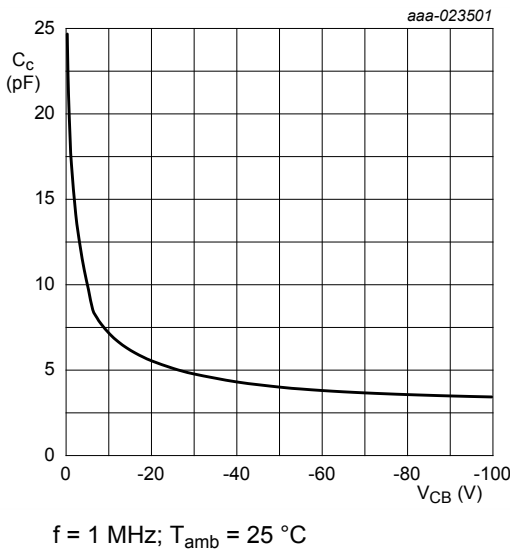
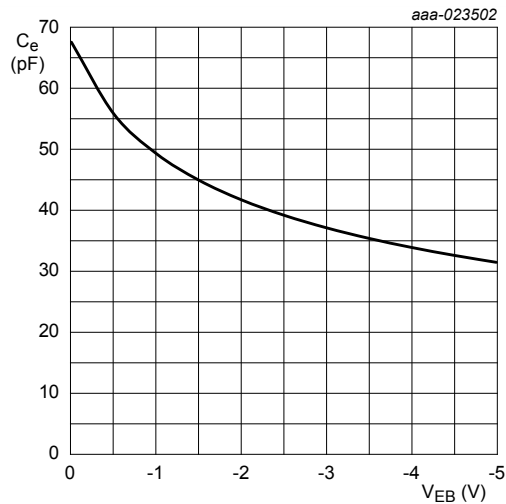
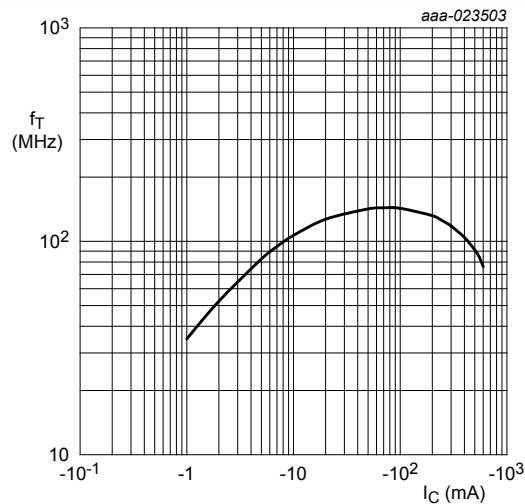


Fig. 15. Collector capacitance as a function of collector-base voltage; typical values



$f = 1$ MHz; $T_{amb} = 25$ °C

Fig. 16. Emitter capacitance as a function of emitter-base voltage; typical values



$V_{CE} = -5$ V
 $f = 100$ MHz; $T_{amb} = 25$ °C

Fig. 17. Transition frequency as a function of collector current; typical values

8. Test information

8.1. Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

9. Package outline

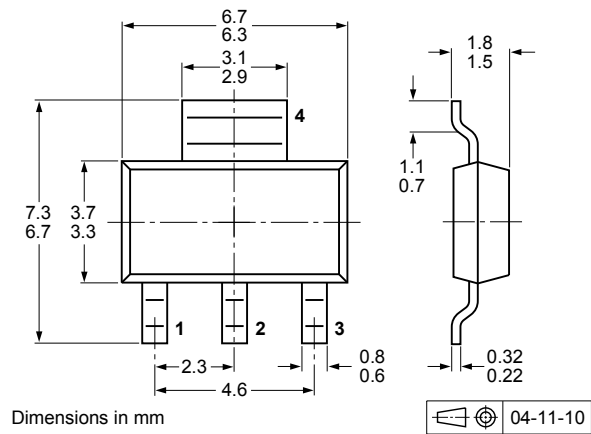
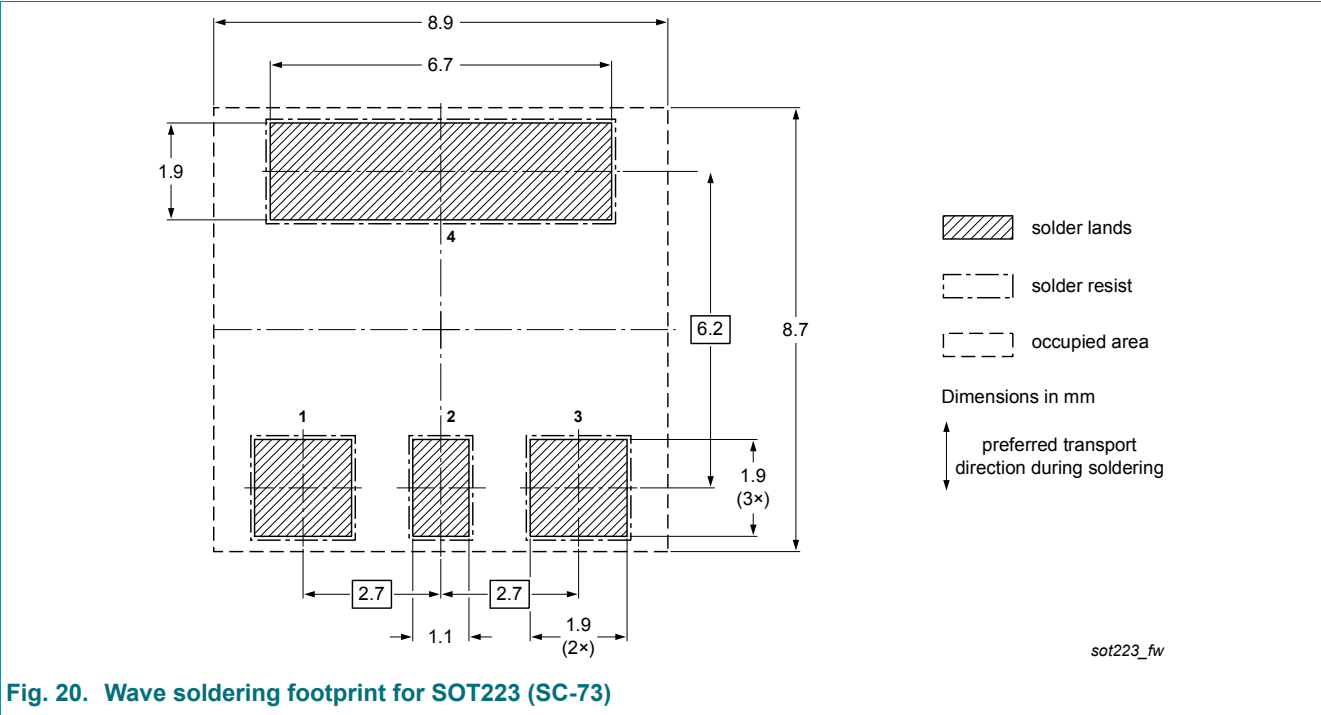
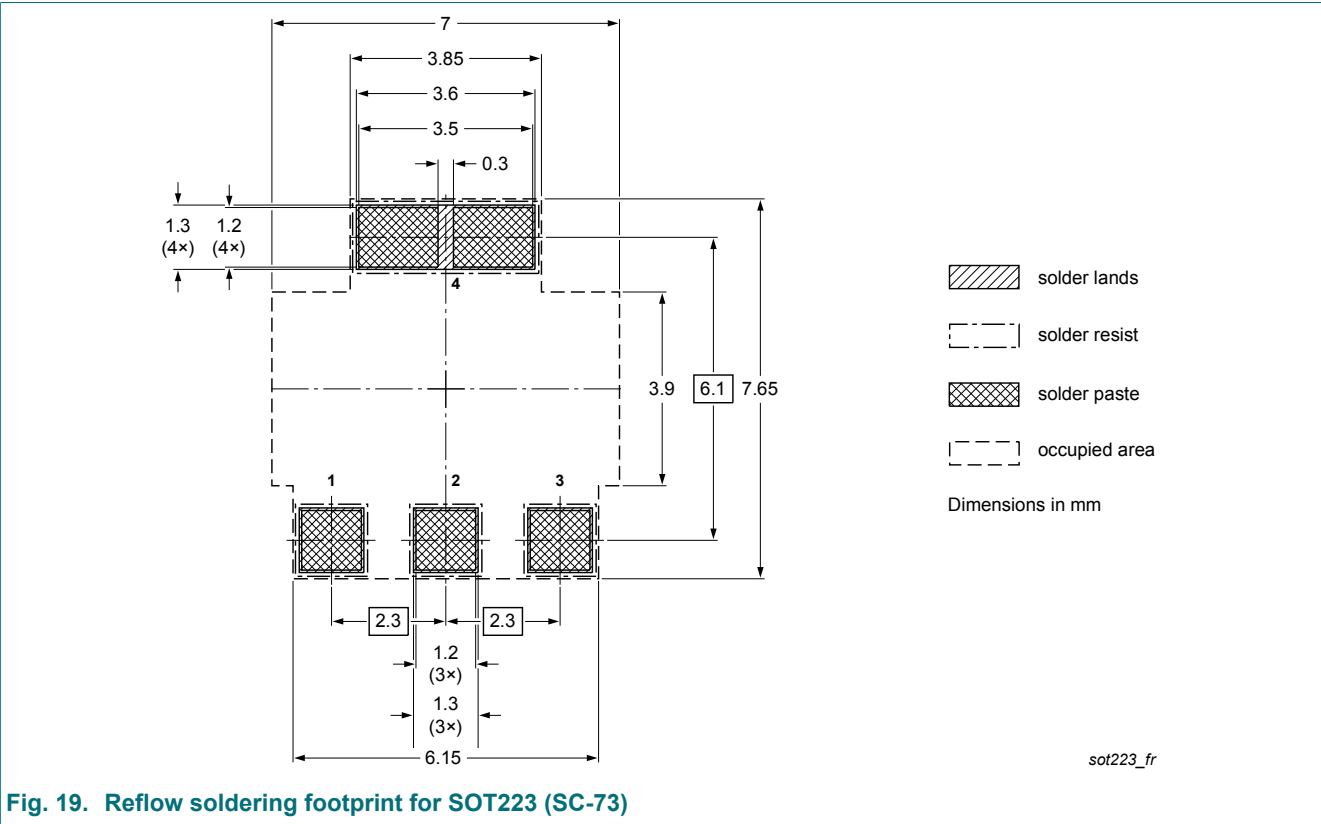


Fig. 18. Package outline SOT223 (SC-73)

10. Soldering



11. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BCP51T_SER v.1	20190429	Product data sheet	-	-

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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Contents

1. Product profile.....	1
1.1. General description.....	1
1.2. Features and benefits.....	1
1.3. Applications.....	1
1.4. Quick reference data.....	1
2. Pinning information.....	2
3. Ordering information.....	2
4. Marking.....	2
5. Limiting values.....	3
6. Thermal characteristics.....	5
7. Characteristics.....	7
8. Test information.....	10
8.1. Quality information.....	10
9. Package outline.....	10
10. Soldering.....	11
11. Revision history.....	12
12. Legal information.....	13

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Date of release: 29 April 2019